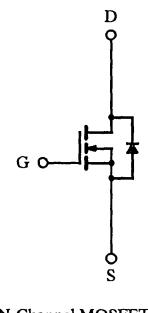
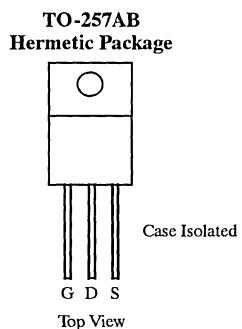


N-Channel Enhancement-Mode Transistor

Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
100	0.15	13

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	13	A
		8.0	
Pulsed Drain Current	I_{DM}	48	W
Maximum Power Dissipation	P_D	50	
		20	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C
Lead Temperature ($1/16''$ from case for 10 sec.)	T_L	300	

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N/P-Channel
MOSFETs

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R_{thJA}	80	2.5	°C/W
Maximum Junction-to-Case	R_{thJC}			
Case-to-Sink	R_{thCS}	1.0		

Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ ^a	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 80 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			25	
		$V_{\text{DS}} = 80 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	μA
On-State Drain Current ^b	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} = 10 \text{ V}, V_{\text{GS}} = 10 \text{ V}$	13.0			A
Drain-Source On-State Resistance ^b	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10 \text{ V}, I_D = 8.0 \text{ A}$		0.12	0.15	
		$V_{\text{GS}} = 10 \text{ V}, I_D = 8.0 \text{ A}, T_J = 125^\circ\text{C}$		0.22	0.27	Ω
Forward Transconductance ^b	g_{fs}	$V_{\text{DS}} = 15 \text{ V}, I_D = 8.0 \text{ A}$	4.0	5.0		S
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 25 \text{ V}, f = 1 \text{ MHz}$		600		
Output Capacitance	C_{oss}			190		pF
Reverse Transfer Capacitance	C_{rss}			35		
Total Gate Charge ^c	Q_g	$V_{\text{DS}} = 50 \text{ V}, V_{\text{GS}} = 10 \text{ V}, I_D = 13 \text{ A}$		17	30	
Gate-Source Charge ^c	Q_{gs}			6	9.0	nC
Gate-Drain Charge ^c	Q_{gd}			9	20	
Turn-On Delay Time ^c	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50 \text{ V}, R_L = 3.8 \Omega$ $I_D \approx 13 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_G = 7.5 \Omega$		7	30	
Rise Time ^c	t_r			45	80	ns
Turn-Off Delay Time ^c	$t_{\text{d}(\text{off})}$			30	60	
Fall Time ^c	t_f			10	40	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				13	
Pulsed Current	I_{SM}				48	A
Diode Forward Voltage ^b	V_{SD}	$I_F = 13 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			2.5	
Reverse Recovery Time	t_{rr}	$I_F = 13 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}$		100	300	ns
Reverse Recovery Charge	Q_{rr}			0.7		μC

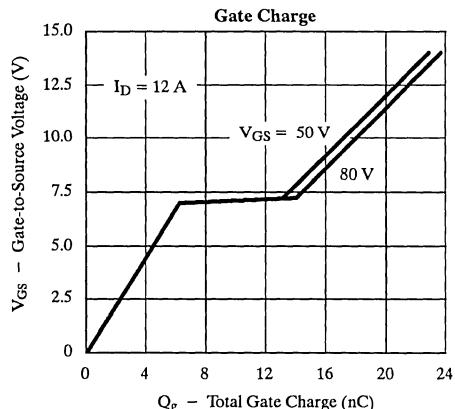
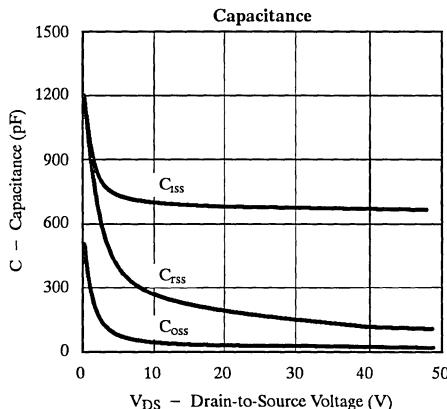
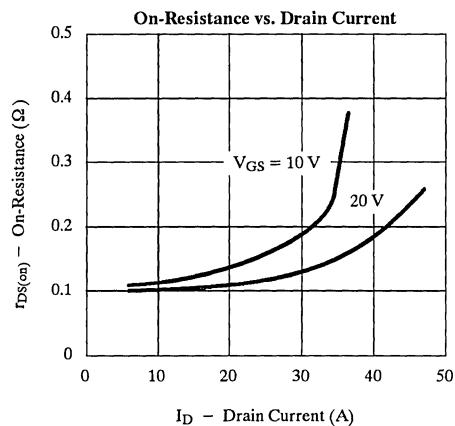
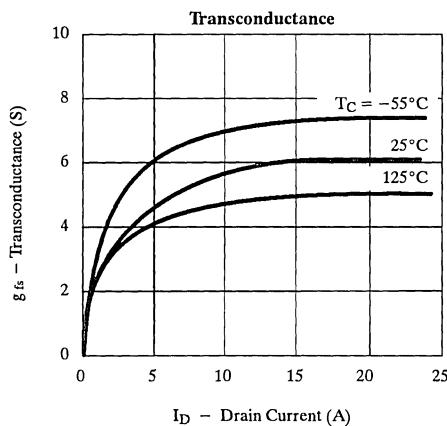
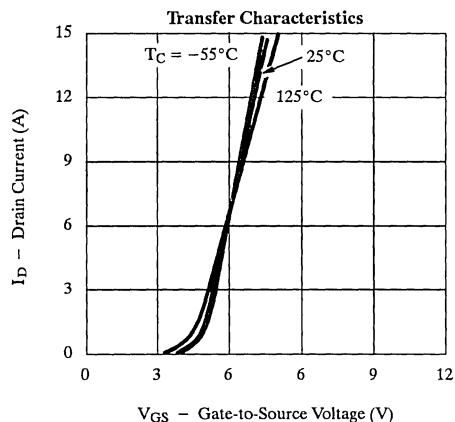
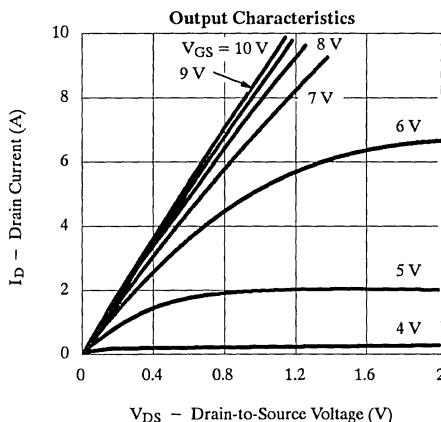
Notes:

a. For design aid only; not subject to production testing.

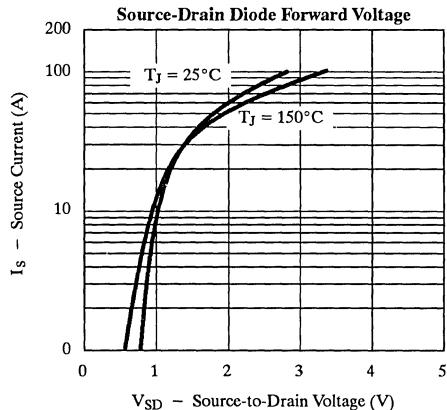
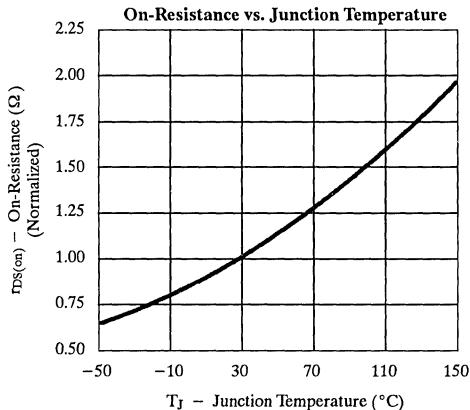
b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

c. Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)



Typical Characteristics (25°C Unless Otherwise Noted)



Thermal Ratings

